Infrared Transceiver, 9.6 kbit/s to 115.2 kbit/s (SIR)





20206-1

DESCRIPTION

TFBS4650 is an infrared transceiver that supports data rates up to 115 kbit/s per the IrDA standard. The link distance is up to 1 meter. The transceiver includes a PIN photodiode, an infrared emitter, and a low-power control IC. These components have not been qualified according to automotive specifications.

FEATURES

- Compliant to the IrDA physical layer specification
- Standard IrDA link distance of 1 m
- Low power consumption, typically less than 70 μA
- Less than 1 μA in shutdown mode
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>





ROHS
COMPLIANT
HALOGEN
FREE
GREEN
(5-2008)

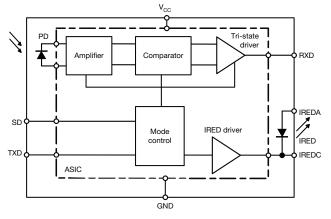
APPLICATIONS

- Short-distance wireless communication and data transfer
- Use in environments where RF is problematic

DESIGN SUPPORT TOOLS

- 3D model
- Window size calculator
- Symbols and terminology
- IRDC protocol
- Reference layouts and circuit diagrams

FUNCTIONAL BLOCK DIAGRAM



19283

LINKS TO ADDITIONAL RESOURCES







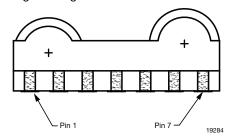
| PRODUCT SUM | IMARY | | | | |
|-------------|-----------------------|---|----------------------|-----------------------------|--------------------------------|
| PART NUMBER | DATA RATE (kbit/s) | DIMENSIONS H x L x W (mm x mm x mm) | LINK DISTANCE (m) | OPERATING VOLTAGE (V) | IDLE SUPPLY CURRENT (mA) |
| TFBS4650 | 115.2 | 1.6 x 6.8 x 2.8 | 0 to ≥ 0.3 | 2.4 to 5.5 | 0.075 |

| PARTS TABLE | | |
|--------------|---|----------|
| PART | DESCRIPTION | QTY/REEL |
| TFBS4650-TR1 | Oriented in carrier tape for side view surface mounting | 1000 pcs |
| TFBS4650-TR3 | Oriented in carrier tape for side view surface mounting | 2500 pcs |
| TFBS4650-TT3 | Oriented in carrier tape for top view surface mounting | 2500 pcs |

| PIN DESCR | RIPTION | | | |
|------------|-----------------|--|-----|--------|
| PIN NUMBER | SYMBOL | DESCRIPTION | I/O | ACTIVE |
| 1 | IREDA | IRED anode, connected via a current limiting resistor to V_{CC2} . A separate unregulated power supply can be used. | | |
| 2 | IREDC | IRED cathode, do not connect for standard operation. | | |
| 3 | TXD | Transmitter data input. Setting this input above the threshold turns on the transmitter. This input switches the IRED with the maximum transmit pulse width of about 100 μ s. | I | High |
| 4 | RXD | Receiver output. Normally high, goes low for a defined pulse duration with the rising edge of the optical input signal. Output is a CMOS tri-state driver, which swings between ground and V _{CC} . Receiver echoes transmitter output. | 0 | Low |
| 5 | SD | Shutdown. Logic low at this input enables the receiver, enables the transmitter, and un-tri-states the receiver output. It must be driven high for shutting down the transceiver. | I | High |
| 6 | V _{CC} | Power supply, 2.4 V to 5.5 V. This pin provides power for the receiver and transmitter drive section. Connect V_{CC1} via an optional filter. | | |
| 7 | GND | Ground | | |

PINOUT

TFBS4650, bottom view weight 0.05 g



Definitions:

In the Vishay transceiver datasheets the following nomenclature is used for defining the IrDA operating modes:

- SIR: 2.4 kbit/s to 115.2 kbit/s, equivalent to the basic serial infrared standard with the physical layer version IrPhy 1.0
- MIR: 576 kbit/s to 1152 kbit/s
- FIR: 4 Mbit/sVFIR: 16 Mbit/s

MIR and FIR were implemented with IrPhy 1.1, followed by IrPhy 1.2, adding the SIR low power standard. IrPhy 1.3 extended the low power option to MIR and FIR and VFIR was added with IrPhy 1.4. A new version of the standard in any case obsoletes the former version.



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| ABSOLUTE MAXIMUM RATII | NGS | | | | | |
|--|---|------------------------|------|------|-----------------------|------|
| PARAMETER | TEST CONDITIONS | SYMBOL | MIN. | TYP. | MAX. | UNIT |
| Supply voltage range, transceiver | 0 V < V _{CC2} < 6 V | V _{CC1} | -0.5 | - | 6 | V |
| Supply voltage range, transmitter | 0 V < V _{CC1} < 6 V | V_{CC2} | -0.5 | - | 6 | V |
| Voltage at RXD | All states | V _{IN} | -0.5 | - | V _{CC} + 0.5 | V |
| Input voltage range, transmitter TXD | Independent of V _{CC1} or V _{CC2} | V _{IN} | -0.5 | - | 6 | V |
| Input currents | For all pins, except IRED anode pin | | -40 | - | 40 | mA |
| Output sinking current | | | - | - | 20 | mA |
| Power dissipation | | P_D | - | - | 250 | mW |
| Junction temperature | | T_J | - | - | 125 | °C |
| Ambient temperature range (operating) | | T _{amb} | -30 | - | +85 | °C |
| Storage temperature range | | T _{stg} | -40 | - | +100 | °C |
| Soldering temperature (1) | See section "Recommended Solder Profile" | | - | - | - | °C |
| Repetitive pulse output current | < 90 μs, t _{on} < 20 % | I _{IRED} (RP) | - | - | 500 | mA |
| Average output current (transmitter) | | I _{IRED} (DC) | - | - | 100 | mA |
| Thermal resistance junction-to-ambient | JESD51 | R_{thJA} | - | 300 | - | K/W |

Notes

- Reference point pin, ground unless otherwise noted
 Typical values are for DESIGN AID ONLY, not guaranteed nor subject to production testing
- (1) Sn/lead (Pb)-free soldering. The product passed Vishay's standard convection reflow profile soldering test

| EYE SAFETY INFORMATION | |
|---|----------------|
| STANDARD | CLASSIFICATION |
| IEC/EN 60825-1 (2007-03), DIN EN 60825-1 (2008-05) "SAFETY OF LASER PRODUCTS - Part 1: equipment classification and requirements", simplified method | Class 1 |
| IEC 62471 (2006), CIE S009 (2002) "Photobiological Safety of Lamps and Lamp Systems" | Exempt |
| DIRECTIVE 2006/25/EC OF THE EUROPEAN PARLIAMENT AND OF THE COUNCIL of 5 th April 2006 on the minimum health and safety requirements regarding the exposure of workers to risks arising from physical agents (artificial optical radiation) (19 th individual directive within the meaning of article 16(1) of directive 89/391/EEC) | Exempt |

Note

• Vishay transceivers operating inside the absolute maximum ratings are classified as eye safe according the above table



| PARAMETER | TEST CONDITIONS | SYMBOL | MIN. | TYP. | MAX. | UNIT |
|--|---|-------------------|-----------------------|------|------------------------|------|
| TRANSCEIVER | | 1 | | | | |
| Supply voltage range | | V _{CC} | 2.4 | - | 5.5 | V |
| Dynamic supply current | | • | | | | |
| Idle, dark ambient | $\begin{array}{l} \text{SD = low (< 0.8 V),} \\ \text{E}_{\text{eamb}} = 0 \text{ klx,} \\ \text{E}_{\text{e}} < 4 \text{ mW/m}^2 \\ \text{-25 °C} \le \text{T} \le +85 \text{ °C} \end{array}$ | Icc | - | 90 | 130 | μΑ |
| Idle, dark ambient | $\begin{aligned} \text{SD} &= \text{low (< 0.8 V)}, \\ \text{E}_{\text{eamb}} &= 0 \text{ klx}, \\ \text{E}_{\text{e}} &< 4 \text{ mW/m}^2 \\ \text{T} &= +25 \text{ °C} \end{aligned}$ | Icc | - | 75 | 1 | μΑ |
| Peak supply current during transmission | SD = low, TXD = high | I _{ccpk} | - | 2 | 3 | mA |
| Shutdown supply current dark ambient | SD = high (> V _{CC} - 0.5 V), T = 25 °C, E _e = 0 klx | I _{SD} | - | - | 0.1 | μΑ |
| Shutdown supply current, dark ambient | SD = high (> V_{CC} - 0.5 V), -25 °C ≤ T ≤ +85 °C | I _{SD} | - | - | 1 | μΑ |
| Operating temperature range | | T _A | -30 | - | +85 | °C |
| Input voltage low (TXD, SD) | | V _{IL} | -0.5 | - | 0.5 | V |
| Input voltage high | $V_{CC} = 2.4 \text{ V to } 5.5 \text{ V}$ | V _{IH} | V _{CC} - 0.5 | - | 6 | V |
| Input voltage threshold SD | $V_{CC} = 2.4 \text{ V to } 5.5 \text{ V}$ | | 0.9 | 1.35 | 1.8 | V |
| Output voltage low | V_{CC} = 2.4 V to 5.5 V C_{LOAD} = 15 pF | V _{OL} | -0.5 | - | V _{CC} x 0.15 | V |
| Output voltage high | $V_{CC} = 2.4 \text{ V to } 5.5 \text{ V}$ $C_{LOAD} = 15 \text{ pF}$ | V _{OH} | V _{CC} x 0.8 | - | V _{CC} + 0.5 | V |
| RXD to V _{CC} pull-up impedance | $SD = V_{CC}$ $V_{CC} = 2.4 \text{ V to 5 V}$ | R _{RXD} | - | 500 | - | kΩ |
| Input capacitance (TXD, SD) | | C _I | - | = | 6 | pF |

Note

[•] Typical values are for design aid only, not guaranteed nor subject to production testing



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| PARAMETER | TEST CONDITIONS | SYMBOL | MIN. | TYP. | MAX. | UNIT |
|---|---|---------------------------------------|-------------------------|-----------|-------------------------|--|
| RECEIVER | | | | | | |
| Sensitivity: minimum irradiance E _e in angular range ⁽¹⁾⁽²⁾ | 9.6 kbit/s to 115.2 kbit/s λ = 850 nm to 900 nm | E _e | - | 40 (4) | 81 (8.1) | mW/m² (μW/cm²) |
| Maximum irradiance E _e in angular range | λ = 850 nm to 900 nm | E _e | 5 (500) | - | - | kW/m ² (mW/cm ²) |
| No receiver output input irradiance (3) | According to IrDA IrPHY 1.4, appendix A1, fluorescent light specification | E _e | 4 (0.4) | - | - | mW/m ² (μW/cm ²) |
| Rise time of output signal | 10 % to 90 %, C _L = 15 pF | t _{r (RXD)} | 20 | = | 100 | ns |
| Fall time of output signal | 90 % to 10 %, C _L = 15 pF | t _{f (RXD)} | 20 | = | 100 | ns |
| RXD pulse width of output signal, 50 % ⁽⁴⁾ | Input pulse width 1.63 µs | t _{PW} | 1.7 | 2 | 2.9 | μs |
| Receiver start up time | Power on delay | | - | 100 | 150 | μs |
| Latency | | tL | - | 50 | 200 | μs |
| TRANSMITTER (new surface en | mitter values introduced via PCN) | | | | | |
| IRED operating current limitation | No external resistor for current limitation (4) | I _D | 200 | 300 | 430 | mA |
| Forward voltage of built-in IRED | I _f = 300 mA | V_{f} | 1.4 | 1.8 | 1.9 | V |
| Output leakage IRED current | TXD = 0 V, 0 < V _{CC1} < 5.5 V | I _{IRED} | -1 | 0.01 | 1 | μA |
| | $\alpha = 0^{\circ}$, 15°, TXD = high, SD = low | le | 40 | 250 | 400 | mW/sr |
| Output radiant intensity | $V_{CC1} = 5 \text{ V}, \ \alpha = 0^{\circ}, \ 15^{\circ}, \ TXD = \text{low or SD} = \text{high} \ (\text{receiver is inactive as long as SD} = \text{high})$ | l _e | - | - | 0.04 | mW/sr |
| Output radiant intensity, angle of half intensity | | α | - | ± 30 | - | 0 |
| Peak - emission wavelength (5) | | λρ | 870 | - | 910 | nm |
| Spectral bandwidth | | Δλ | - | 45 | - | nm |
| Optical rise time, fall time | | t _{ropt} , t _{fopt} | 10 | 50 | 300 | ns |
| Optical output pulse duration | Input pulse width 1.6 < t _{TXD} < 23 µs | t _{opt} | t _{TXD} - 0.15 | - | t _{TXD} + 0.15 | μs |
| | Input pulse width t _{TXD} ≥ 23 µs | t _{opt} | 23 | 50 | 100 | μs |
| Optical overshoot | | | - | - | 25 | % |

Notes

- · Typical values are for design aid only, not guaranteed nor subject to production testing
- (1) This parameter reflects the backlight test of the IrDA physical layer specification to guarantee immunity against light from fluorescent lamps.
- (2) IrDA sensitivity definition: minimum irradiance E_e in angular range, power per unit area. The receiver must meet the BER specification while the source is operating at the minimum intensity in angular range into the minimum half-angular range at the maximum link length
- (3) Maximum irradiance E_e in angular range, power per unit area. The optical delivered to the detector by a source operating at the maximum intensity in angular range at minimum link length must not cause receiver overdrive distortion and possible related link errors. If placed at the active output interface reference plane of the transmitter, the receiver must meet its bit error ratio (BER) specification. For more definitions see the document "Symbols and Terminology" on the Vishay website
- (4) RXD output is edge triggered by the rising edge of the optical input signal. The output pulse duration is independent of the input pulse duration
- (5) The radiant intensity can be adjusted by the external current limiting resistor to adapt the intensity to the desired value. The given value is for minimum current consumption. This transceiver can be adapted to > 50 cm operation by increasing the current to > 200 mA, e.g. operating the transceiver without current control resistor (i.e. R1 = 0 Ω) and using the internal current control

| TRUTH TABI | LE | | | |
|------------|--------------|--|--|----------------|
| | IN | IPUTS | OUTPUTS | |
| SD | TXD | OPTICAL INPUT IRRADIANCE mW/m ² | RXD | TRANSMITTER |
| High | х | x | Tri-state floating with a weak pull-up to the supply voltage | 0 |
| Low | High | x | Low (echo on) | I _e |
| Low | High > 50 μs | x | High | 0 |
| Low | Low | < 4 | High | 0 |
| Low | Low | > min. irradiance E _e < max. irradiance E _e | Low (active) | 0 |
| Low | Low | > max. irradiance E _e | x | 0 |

RECOMMENDED CIRCUIT DIAGRAM

Operated at a clean low impedance power supply the TFBS4650 needs only one additional external component when the IRED drive current should be minimized for minimum current consumption according the low power IrDA standard. When combined operation in IrDA and remote control is intended no current limiting resistor is recommended.

However, depending on the entire system design and board layout, additional components may be required (see Fig. 1). When long wires are used for bench tests, the capacitors are mandatory for testing rise / fall time correctly.

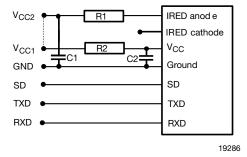


Fig. 1 - Recommended Application Circuit

The capacitor C1 is buffering the supply voltage $V_{\rm CC2}$ and eliminates the inductance of the power supply line. This one should be a small ceramic version or other fast capacitor to guarantee the fast rise time of the IRED current. The resistor R1 is necessary for controlling the IRED drive current when the internally controlled current is too high for the application.

Vishay transceivers integrate a sensitive receiver and a built-in power driver. The combination of both needs a careful circuit board layout. The use of thin, long, resistive and inductive wiring should be avoided. The inputs (TXD, SD) and the output RXD should be directly (DC) coupled to the I/O circuit.

The capacitor C2 combined with the resistor R2 is the low pass filter for smoothing the supply voltage.

As already stated above R2, C1 and C2 are optional and depend on the quality of the supply voltages V_{CCx} and

injected noise. An unstable power supply with dropping voltage during transmission may reduce the sensitivity (and transmission range) of the transceiver.

The placement of these parts is critical. It is strongly recommended to position C2 as close as possible to the transceiver power supply pins.

When connecting the described circuit to the power supply, low impedance wiring should be used.

In case of extended wiring the inductance of the power supply can cause dynamically a voltage drop at V_{CC2} . Often some power supplies are not able to follow the fast current is rise time. In that case another 10 μF cap at V_{CC2} will be helpful.

Keep in mind that basic RF-design rules for circuit design should be taken into account. Especially longer signal lines should not be used without termination. See e.g. "The Art of Electronics" Paul Horowitz, Wienfield Hill, 1989, Cambridge University Press, ISBN: 0521370957.

| RECOMMENDED APPLICATION CIRCUIT COMPONENTS | | | | |
|--|--|--|--|--|
| COMPONENT | RECOMMENDED VALUE | | | |
| C1, C2 | 0.1 μF, Ceramic Vishay part# VJ 1206 Y 104 J XXMT | | | |
| R1 | See table below | | | |
| R2 | 47 Ω, 0.125 W (V _{CC1} = 3 V) | | | |

| RECOMMENI | RECOMMENDED RESISTOR R1 (Ω) | | | | |
|-------------------------|---|--|--|--|--|
| V _{CC2} (V) | MINIMIZED CURRENT CONSUMPTION, IrDA LOW POWER COMPLIANT | | | | |
| 2.7 | 24 | | | | |
| 3 | 30 | | | | |
| 3.3 | 36 | | | | |



ASSEMBLY INSTRUCTIONS

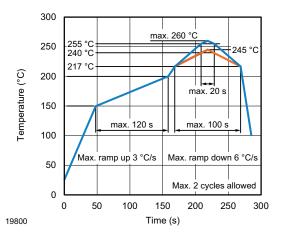
Reflow Soldering

- Reflow soldering must be done within 72 h while stored under a max. temperature of 30 °C, 60 % RH after opening the dry pack envelope
- Set the furnace temperatures for pre-heating and heating in accordance with the reflow temperature profile as shown in the diagram. Exercise extreme care to keep the maximum temperature below 260 °C. The temperature shown in the profile means the temperature at the device surface. Since there is a temperature difference between the component and the circuit board, it should be verified that the temperature of the device is accurately being measured
- Handling after reflow should be done only after the work surface has been cooled off

Manual Soldering

- Use a soldering iron of 25 W or less. Adjust the temperature of the soldering iron below 300 °C
- Finish soldering within 3 s
- Handle products only after the temperature has cooled off

VISHAY LEAD (Pb)-FREE REFLOW SOLDER PROFILE





PACKAGE DIMENSIONS in millimeters

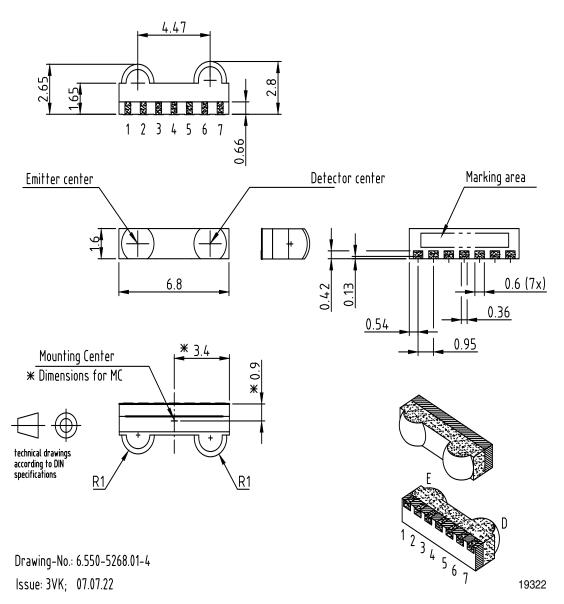


Fig. 2 - TFBS4650 Mechanical Dimensions, Tolerance ± 0.2 mm, if not otherwise mentioned

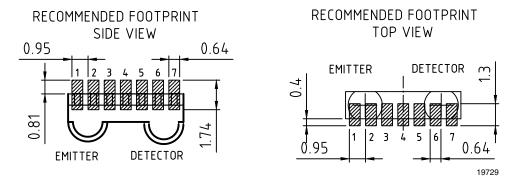
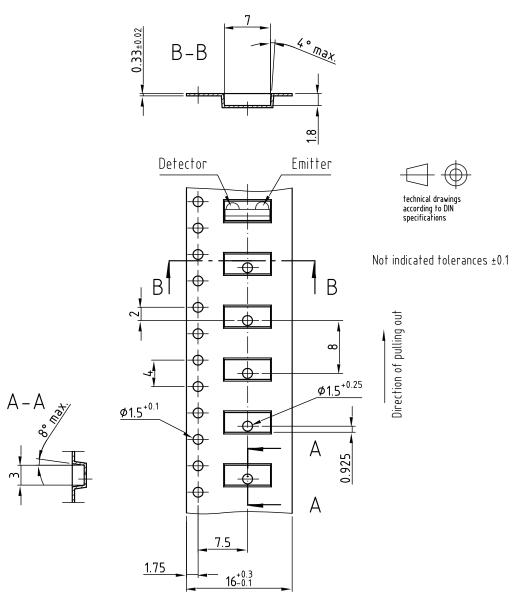


Fig. 3 - TFBS4650 Soldering Footprint, Tolerance \pm 0.2 mm, if not otherwise mentioned

TAPE DIMENSIONS FOR TR1 AND TR3 in millimeters

Tape for Side View Oriented Parts



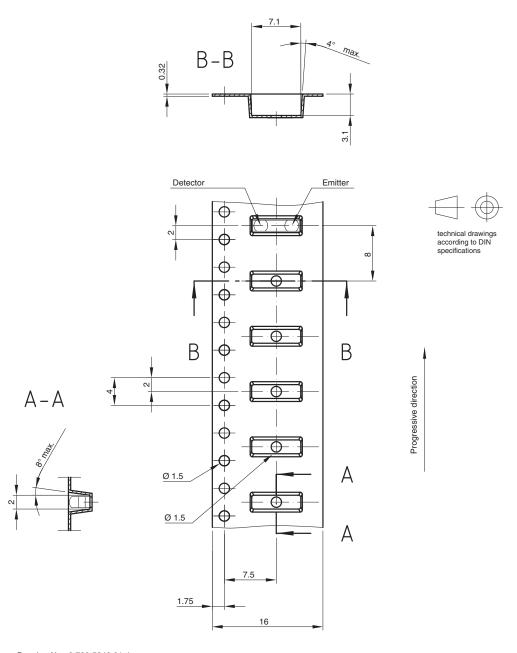
Drawing-No.: 9.700-5296.01-4 Issue: prel. copy; 24.11.04

19285



TAPE DIMENSIONS FOR TT1 in millimeters

Tape for Top View Oriented Parts

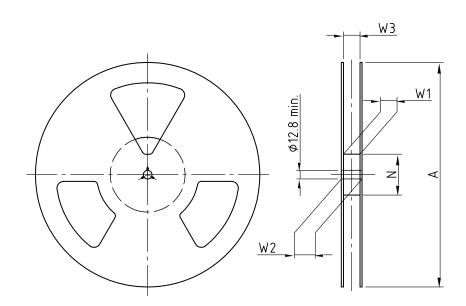


Drawing-No.: 9.700-5340.01-4

Issue: 1; 15.01.09

21663

REEL DIMENSIONS in millimeters



Reel hub 2:1

Drawing-No.: 9.800-5090.01-4 Issue: 1; 29.11.05

14017

Form of the leave open of the wheel is supplier specific.

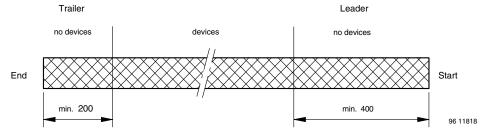
Dimension acc. to IEC EN 60 286-3



technical drawings according to DIN specifications

| TAPING VARIANT | TAPE WIDTH (mm) | A MAX. (mm) | N (mm) | W ₁ MIN. (mm) | W ₂ MAX. (mm) | W ₃ MIN. (mm) | W ₃ MAX. (mm) |
|-------------------|-----------------|----------------|-----------|-----------------------------|-----------------------------|-----------------------------|-----------------------------|
| TT1 / TR1 | 16 | 180 | 60 | 16.4 | 22.4 | 15.9 | 19.4 |
| TT3 / TR3 | 16 | 330 | 50 | 16.4 | 22.4 | 15.9 | 19.4 |

LEADER AND TRAILER DIMENSIONS in millimeters



COVER TAPE PEEL STRENGTH

According to DIN EN 60286-3 0.1 N to 1.3 N 300 ± 10 mm/min. 165° to 180° peel angle

LABEL

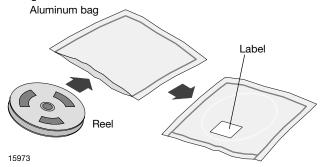
Standard bar code labels for finished goods

The standard bar code labels are product labels and used for identification of goods. The finished goods are packed in final packing area. The standard packing units are labeled with standard bar code labels before transported as finished goods to warehouses. The labels are on each packing unit and contain Vishay Semiconductor GmbH specific data.



DRY PACKING

The reel is packed in an anti-humidity bag to protect the devices from absorbing moisture during transportation and storage.



FINAL PACKING

The sealed reel is packed into a cardboard box.

RECOMMENDED METHOD OF STORAGE

Dry box storage is recommended as soon as the aluminum bag has been opened to prevent moisture absorption. The following conditions should be observed, if dry boxes are not available:

- Storage temperature 10 °C to 30 °C
- Storage humidity ≤ 60 % RH max.

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After more than 72 h under these conditions moisture content will be too high for reflow soldering.

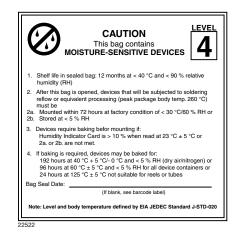
In case of moisture absorption, the devices will recover to the former condition by drying under the following condition:

192 h at 40 °C + 5 °C / - 0 °C and < 5 % RH (dry air / nitrogen) or

96 h at 60 °C + 5 °C and < 5 % RH for all device containers or

24 h at 125 °C + 5 °C not suitable for reel or tubes.

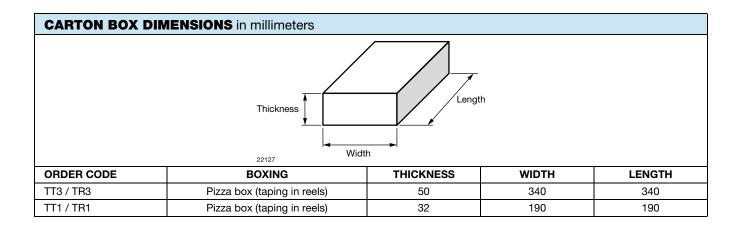
An EIA JEDEC $^{\circledR}$ standard J-STD-020 level 4 label is included on all dry bags.



EIA JEDEC standard J-STD-020 level 4 label is included on all dry bags

OUTER PACKAGING

The sealed reel is packed into a pizza box.





| PLAIN WRITING | ABBREVIATION | LENGTH | |
|-----------------------|--------------|--------------|--|
| | ABBREVIATION | | |
| Item-description | - | 18 | |
| Item-number | INO | 8 | |
| Selection-code | SEL | 3 | |
| LOT-/serial-number | BATCH | 10 | |
| Data-code | COD | 3 (YWW) | |
| Plant-code | PTC | 2 | |
| Quantity | QTY | 8 | |
| Accepted by | ACC | - | |
| Packed by | PCK | - | |
| Mixed code indicator | MIXED CODE | - | |
| Origin | xxxxxx+ | Company logo | |
| Long bar code top | Туре | Length | |
| Item-number | N | 8 | |
| Plant-code | N | 2 | |
| Sequence-number | X | 3 | |
| Quantity | N | 8 | |
| Total length | - | 21 | |
| Short bar code bottom | Туре | Length | |
| Selection-code | X | 3 | |
| Data-code | N | 3 | |
| Batch-number | X | 10 | |
| Filter | - | 1 | |
| Total length | - | 17 | |

ESD PRECAUTION

Proper storage and handling procedures should be followed to prevent ESD damage to the devices especially when they are removed from the antistatic shielding bag. Electrostatic sensitive devices warning labels are on the packaging.

VISHAY SEMICONDUCTORS STANDARD BAR CODE LABELS

The Vishay Semiconductors standard bar code labels are printed at final packing areas. The labels are on each packing unit and contain Vishay Semiconductors specific data.







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